

# Model 1380100-XXX 20 MHz, Stratum 3E OCXO

#### **Features**

- Industry standard 20 x 12.7 mm SMT package
- Stratum 3E per GR-1244-CORE
- 3.3V operation
- Low Phase Noise
- Tape and Reel packaging

# **Applications**

- Telecom Switching
- Wireless Communication
- Timing over Packet



20 x 12.7 x 11 mm

#### Description

The CTS model 1380100 is a low cost, small size, high performance OCXO. The high quality CTS Quartz Crystal used in this OCXO offers high stability and low jitter/phase noise, making it the ideal choice for any telecommunications system

# **Electrical Specifications**

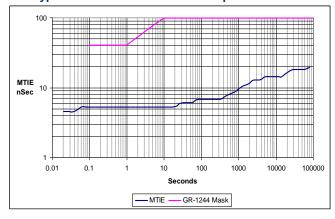
Parameter	Conditions & Remarks	Min	Typical	Max	Unit
Operating Conditions					
Operating Temperature Range		-40	-	+85	°C
Supply Voltage	3.3V	3.135	3.3	3.465	Vdc
Davier Canadantian	Warm up	-	1.8	2.5	- W
Power Consumption	Steady state @ 25°C	-	0.75	1.0	
Load	Output to Ground	5	10	15	pf
Frequency Stability					
Frequency	F <sub>NOM</sub>		20.000		MHz
Calibration	$\Delta$ F/F <sub>NOM</sub> ; at time of shipment	-	±300	+500	ppb
Temperature Stability	See options table	-	7	10	ppb pk-pk
Voltage Stability	±5%	-	±1	±2	ppb
Aging	Per day, at time of shipment	-	±0.5	±1	ppb/day
	First year	-	-	±100	ppb
	10 years	-	-	±700	ppb
Holdover (24 hours)	Inclusive of operating temp and 24 hours aging drift – See Table 1	-	-	11	ppb pk-pk
Total Free-Run Accuracy	Under all conditions for 10 years	-	-	±2.5	ppm



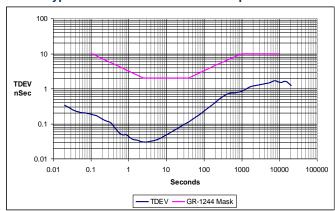
# **Electrical Specifications**

Parameter	Conditions & Remarks	Min	Typical	Max	Unit	
Operating Conditions	Continued					
Drift	24 hours at constant temperature – See Table 1	-	-	±1	ppb	
	1.0 sec	-	<0.01	0.02		
Short Torm Stability	10 sec	-	0.01	0.03		
Short Term Stability	100 sec	-	0.02	0.05	ppb	
ADEV (in still air)	1000 sec	-	0.05	0.1		
	10,000 sec	-	0.07	0.2		
Wander Generation	MTIE and TDEV per Stratum 3E requirements per GR-1244-CORE					
Warm-Up Time	$T_A = 25$ °C; to within 10 ppb of frequency @ 30 minutes	-	-	5	minutes	
Output Parameters –	HCMOS					
Amplitude	$V_{OL}$	-	-	10% V <sub>CC</sub>	\ /	
	$V_{OH}$	90% V <sub>CC</sub>	-	-	V	
Rise / Fall Times	10% to 90% @ 10pf load	-	3	5	nsec	
Duty Cycle	@ 50% of output signal	45	50	55	%	
Spurious		-	-	-70	dBc	
Phase Noise	Offset = 10Hz	-	-110	-		
	100Hz	-	-130	-	dBc/Hz	
	1KHz	-	-140	-	UDC/ HZ	
	10KHz	-	-148	-		

#### **Typical Wander Generation MTIE performance**



#### **Typical Wander Generation TDEV performance**





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Table 1 – Aging Recovery

Time Off	Minimum power on time to	
Time On	recover daily aging rate	
≤ 1 day	24 hours	
< 1 week	3 days	
< 1 month	6 days	

# **Options and Part Number**

Dash No.	Package	Operating Temp. Range	Part Number
-001	SMT (Fig 1)	-20°C to +70°C	1380100-001
-002	SMT (Fig 1)	-40°C to +85° <b>C</b>	1380100-002
-003	Thru-Hole (Fig 2)	-20°C to +70°C	1380100-003
-004	Thru-Hole (Fig 2)	-40°C to +85° <b>C</b>	1380100-004

### Mechanical and Environmental

Soldering	Maximum reflow temperature, 245°C for 10 seconds, 240°C for 20 seconds, per IPC/JEDEC J-STD-020C		
MSL	Level 1		
RoHS	Lead-Free. Fully compliant to RoHS Directive 2011/65/EU		
Shock	500 G's, 1msec, 5 shocks in each of 6 directions		
Sinusoidal Vibration	10 Hz to 55 Hz with a double amplitude of 1.5 mm, 10 g's peak from 55 Hz to 2000Hz, for		
	30 minutes in each of three perpendicular directions		
Random Vibration	5.35 G's RMS. 20 to 500 Hz, per MIL-STD-202F,		
	Method 214, 15 minutes each axis.		
Seal	Hermetic		
Marking Permanency	Per MIL-STD-202F, Method 215J		
Packaging	Tape and Reel for Surface Mount package; Bulk pack in foam for Thru-Hole package		
Storage Temp Range	-40 to +85°C		



Figure 1 – Package Drawing – Surface Mount

Pad termination finish: Gold Flash <10 micro inch, over Ni plated Cu

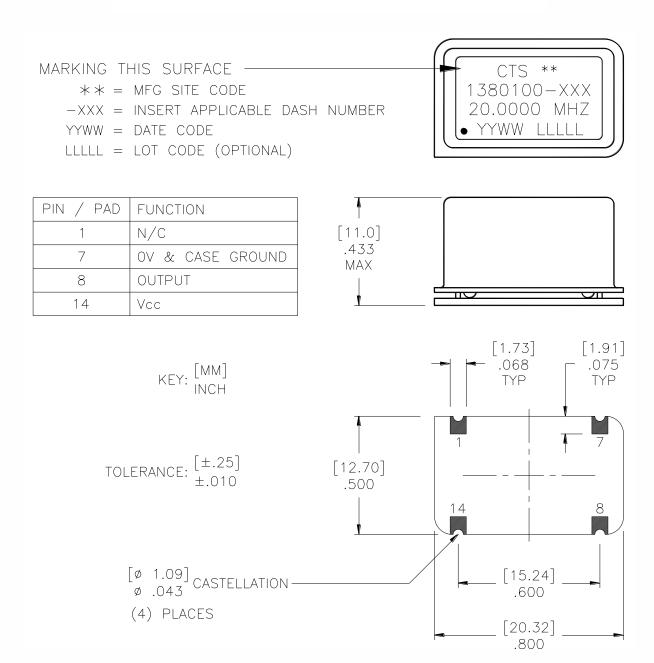
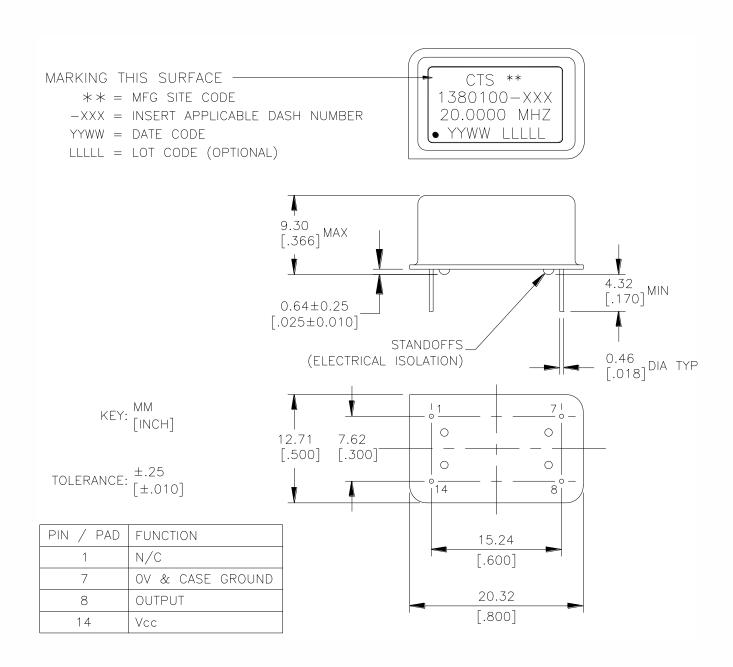




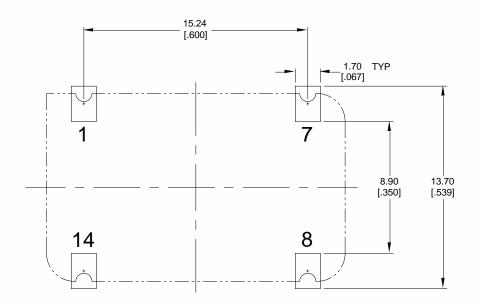
Figure 2 – Package Drawing – Thru Hole

Lead termination finish: Solder Coated, Sn96.5/Ag3.5



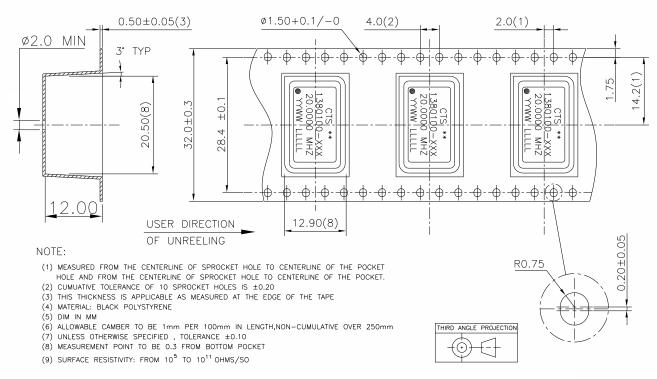


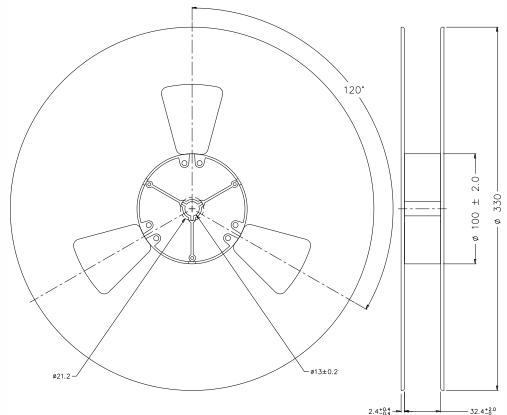
### **Recommended Land Pattern**





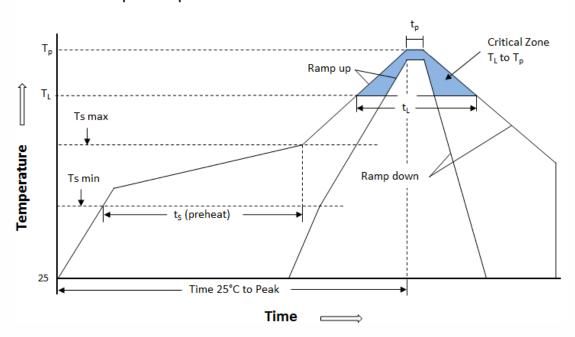
# Packing: Tape and Reel







# Reflow profile per IPC/JEDEC J-STD-020C



Note: The temperatures shown below represent the device body temperature

Ts max to T <sub>L</sub> (Ramp-up Rate)	3°C/second max	
Preheat		
Temperature Min(Ts Min)	150°C	
Temperature Typical( Ts Typ)	175°C	
Temperature Max.(Ts Max)	200°C	
Time(ts)	60-180 seconds	
Ram-up Rate(T <sub>L</sub> to Tp)	3°C/second max	
Time Maintained Above:		
Temperature(T <sub>L</sub> )	217°C	
Time(T <sub>L</sub> )	60-150seconds	
Peak Temperature (Tp)	245°C max for 10 seconds	
Time within 5°C of actual peak(tp)	20 seconds	
Ramp-down Rate	6°C/second max	
Tune 25°C to Peak Temperature(t)	8 minutes max	